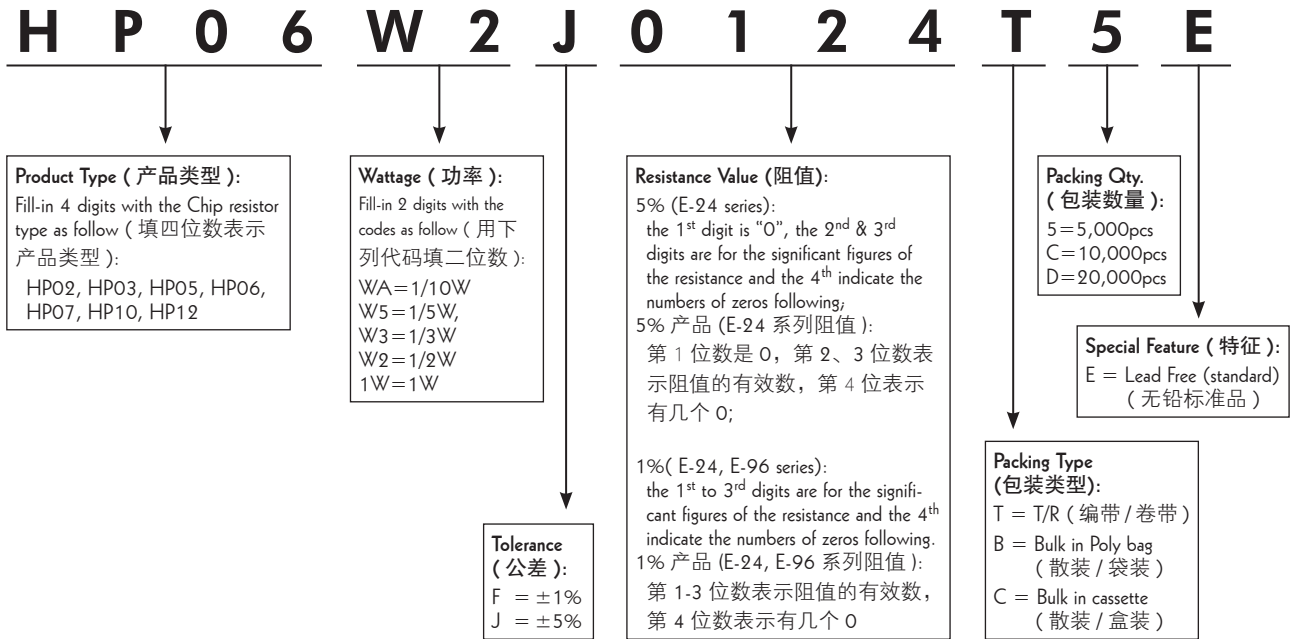


Ordering Procedure (Example: High Power HP06 1/2W 5% 120KΩ T/R-5000)

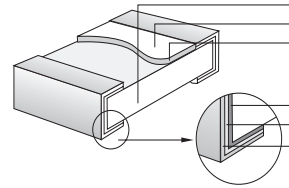
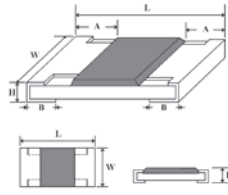
订购方式 (例如: 高功率 HP06 1/2W 5% 120KΩ T/R-5000)



### Feature (特性)

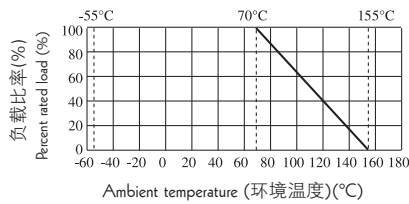
- High power in standard size  
标准尺寸，高功率
- Suitable for both wave & re-flow soldering  
适合波峰焊与回流焊
- Application: AV adapters, LCD back-light, camera strobe etc. 适用于AV适配器, LCD 背光电路, 照相机快门等

### Figures (型状)



1. High purity Alumina substrate (高纯度氧化铝基板)
2. Protective coating (保护层)
3. Resistance element (阻抗元素)
4. Termination (Inner) Ni / Cr [端面(内)镍/铬层]
5. Termination (Between) Ni Barrier [端面(中)镍层]
6. Termination (Outer) Sn [端面(外)锡层(无铅)]

### Derating Curve & Specification (降功率曲线及性能)



Type 类型	Max. Working Voltage 最大工作电压	Max. Overload Voltage 最大过负荷电压	Dielectric Withstanding Voltage 绝缘耐压	Operating Temperature 工作温度范围
HP02	50V	100V	100V	-55°C~155°C
HP03	50V	100V	300V	-55°C~155°C
HP05	150V	300V	500V	-55°C~155°C
HP06	200V	400V	500V	-55°C~155°C
HP07	200V	500V	500V	-55°C~155°C
HP10	200V	500V	500V	-55°C~155°C
HP12	250V	500V	500V	-55°C~155°C

Type 类型	Power Rating at 70°C 功率	L(mm)	W(mm)	H(mm)	A(mm)	B(mm)	Resistance Range of 1% 1%的阻值范围	Resistance Range of 5% 5%的阻值范围
HP02	1/10W	1.00±0.10	0.50 <sup>+0.05</sup> <sub>-0.05</sub>	0.35±0.05	0.20±0.10	0.25±0.10	1Ω~10M	1Ω~10M
HP03	1/5W	1.60±0.10	0.80 <sup>+0.15</sup> <sub>-0.10</sub>	0.45±0.10	0.30±0.20	0.30±0.20	1Ω~10M	1Ω~10M
HP05	1/3W	2.00±0.15	1.25 <sup>+0.15</sup> <sub>-0.10</sub>	0.55±0.10	0.40±0.20	0.40±0.20	1Ω~10M	1Ω~10M
HP06	1/2W	3.10±0.15	1.55 <sup>+0.15</sup> <sub>-0.10</sub>	0.55±0.10	0.45±0.20	0.45±0.20	1Ω~10M	1Ω~10M
HP07	3/4W	3.10±0.10	2.60 <sup>+0.15</sup> <sub>-0.10</sub>	0.55±0.10	0.50±0.25	0.50±0.20	1Ω~10M	1Ω~10M
HP10	1W	5.00±0.10	2.50 <sup>+0.15</sup> <sub>-0.10</sub>	0.55±0.10	0.60±0.25	0.50±0.20	1Ω~10M	1Ω~10M
HP12	2W	6.35±0.10	3.20 <sup>+0.15</sup> <sub>-0.10</sub>	0.55±0.10	0.60±0.25	1.80±0.25	1Ω~10M	1Ω~10M

### Performance Specifications (性能)

Temperature coefficient	温度系数	1Ω~10Ω ≤ ±200PPM/°C 11Ω~10MΩ ≤ ±100PPM/°C
Short-time overload	短时间过负荷	±5%: ±(2.0% + 0.1Ω) Max.(最大) ±1%: ±(1.0% + 0.1Ω) Max.(最大)
Dielectric withstanding voltage	绝缘耐压	No Evidence of flashover, mechanical damage, arcing or insulation breakdown 无击穿, 飞弧及可见机械性损伤
Terminal bending	端子弯曲	±(1.0% + 0.05Ω) Max.(最大)
Soldering heat	耐焊接热	±(1.0% + 0.05Ω) Max.(最大)
Solderability	可焊性	Min. 95% Coverage (最少 95% 覆盖率)
Temperature cycling	温度循环	±5%: ±(1.0% + 0.05Ω) Max.(最大) ±1%: ±(0.5% + 0.05Ω) Max.(最大)
Humidity (Steady state)	恒定湿热	±5%: ±(3.0% + 0.1Ω) Max.(最大) ±1%: ±(0.5% + 0.1Ω) Max.(最大)
Load life in humidity	湿度寿命	±5%: ±(3.0% + 0.1Ω) Max.(最大) ±1%: ±(1.0% + 0.1Ω) Max.(最大)
Load life	负载寿命	±5%: ±(3.0% + 0.1Ω) Max.(最大) ±1%: ±(1.0% + 0.1Ω) Max.(最大)

\* HP02 TCR: 1Ω~10Ω: ±400PPM/°C 11Ω~100Ω: ±200PPM/°C >100Ω: ±100PPM/°C